User's Manual

RZ/G2M

Overview for User's Manual: Hardware

LSI for Rich Graphics Applications

arm

— Preliminary —

Specifications of RZ/G2M

Renesas Electronics
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General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Handling of Unused Pins

   Handle unused pins in accordance with the directions given under Handling of Unused Pins in the manual.

   — The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   — The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.
   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.
   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   — The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   — When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to a product with a different part number, confirm that the change will not lead to problems.

   — The characteristics of Microprocessing unit or Microcontroller unit products in the same group but having a different part number may differ in terms of the internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

RZ/G2M

RZ/G Series, 2nd Generation

R01UH0846EJ0080
Rev.0.80
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1. Overview

1.1 Introduction

The RZ/G2M includes:

- Two 1.5-GHz Arm® Cortex®-A57 MPCore™ cores,
- Four 1.2-GHz Arm® Cortex®-A53 MPCore™ cores,
- Memory controller for LPDDR4-3200 with 32 bits × 2 channels,
- 1 channel for HDMI1.4b output (option) and 1channel for RGB888 output and 1channel for LVDS,
- 2 channels MIPI-CSI2 Video Input, 2channels digital Video Input,
- USB3.0 × 1ch and USB2.0 × 2ch interfaces,
- 800-MHz Arm® Cortex®-R7 core (option),
- Three-dimensional graphics engines,
- Sound processing units,
- SD card host interface,
- PCI Express interface,
- Video processing units,
- CAN interface, and
- EthernetAVB interface.

Note: Arm and Cortex are registered trademark of Arm Limited. All other brands or product names are the property of their respective holders.

Remarks: For items noted as "option", please contact a Renesas Electronics sales representative.

1.2 List of Specifications

1.2.1 Arm Core

Item	Description
System CPU Cortex-A57	• Arm Cortex-A57 Dual MPCore 1.5 GHz • L1 I/D cache 48/32 Kbytes (Parity/ECC) • L2 cache 1 Mbytes (ECC) • NEON™/VFPv4 supported • Security extension supported • Virtualization supported • Armv8 architecture
System CPU Cortex-A53	• Arm Cortex-A53 Quad MPCore 1.2GHz • L1 I/D cache 32/32 KBytes (Parity/ECC), L2 cache 512 Kbytes (ECC) • NEON™/VFPv4 supported • Security extension supported • Virtualization supported • Armv8 architecture

Item	Description
Debug and Trace	• JTAG/SWD I/F supported • ETM-A57/A53 supported (each CPU) • ETF 16 KBytes for program flow trace (each cluster)

1.2.2 CPU Core Peripherals

Item	Description
Clock Pulse Generator (CPG)	• Generates the clocks from external clock (EXTAL). — Maximum Cortex-A57 clock: 1.5 GHz — Maximum Cortex-A53 clock: 1.2 GHz — Maximum 3DGE clock: 600 MHz — Maximum AXI-bus clock: 400 MHz — Maximum SDRAM bus clock: 1600 MHz (LPDDR4-3200) — Maximum media clock: 400 MHz • System-CPU shut down mode control supported • Module-standby mode supported • Includes module reset registers to control reset operation of individual on-chip peripheral modules
System Controller (SYSC)	• Shuts down and restores power to target modules. Target modules: — Cortex-A57 (with independent shutting down of CPUs 0, 1 and SCU+L2 cache) * — Cortex-A53 (with independent shutting down of CPUs 0, 1, 2, 3, and SCU+L2 cache) * — 3DGE — VCP * : SCU and L2 cache are treated as one power-domain. When CPU is working, SCU+L2 cache can't be powered off. • Low leakage standby mode supported.
RESET	• Includes one reset-signal external output port for external modules • Includes Boot Address Register etc.
Pin function controller (PFC)	• Setting multiplexed pin functions for LSI pins Function of the LSI pin selectable by setting the registers in the PFC module • Module selection Enable and disable the functions of LSI pins to which pin functions from multiple pin groups are assigned by setting the registers in the PFC module. • Pull-up/down control for each LSI pin On/off and up/down of the pull register on each LSI pin can be controlled by setting the registers in the PFC module. • Control of SDIO functions SDIO functions, including the driving ability of pins for the SDIF, can be controlled by setting registers of the PFC.
General-purpose I/O (GPIO)	• General-purpose I/O ports • Supports GPIO interrupts

Item	Description
Thermal sensor / Chip Internal Voltage Monitor (THS/CIVM)	• 3 channels of thermal sensor • Programmable 3 temperature level for the sensor, to indicate the temperature level • Interrupt when the temperature reaches programmed

1.2.3 External Bus Module

Item	Description
External Bus Controller for EX-Bus (LBSC)	• EX-BUS interface: max. 16-bit bus • Frequency: 66 MHz or 44.4 MHz • External area divided into several areas and managed — Allocation to space of area 0, area 1. — Area 0 supports 1-MByte memory space (startup mode). — I/F settings, bus width settings, and wait state insertion are possible for each area • SRAM interface — Wait states can be inserted through register settings Period of waiting is set in cycle unit, and the maximum value is 15. — EX_WAIT pin can be used for wait state insertion — Connectable bus widths: 16 bits or 8 bits • Supports external buffer enable/direction control • Supports Burst ROM interface • Supports Byte-control SRAM interface
External Flash Controller	• Supports RPC-IF (Reduced Pin Count interface) flash memory or QSPI flash memory Maximum Frequency 160 MHz (320MB/s) for RPC-IF, 80 MHz (80MB/s) for QSPI (QSPI0) Dual QSPI operation for two 4-bit serial flash memories is also available; 80 MHz (160MB/s) for Dual QSPI (QSPI0+QSPI1).
External Bus Controller for LPDDR4 SDRAM (DBSC4)	• LPDDR4-3200 can be connected directly. Note. The LPDDR4X (JESD209-4-1) is not supported. • 2 channels (32-bit bus mode) • Memory Size: Up to 4GB * * : LPDDR4-SDRAM compliant with JEDEC JESD209-4. (Supports memory with sizes from 512 Mbits to 16 Gbits.) • Auto Refresh/Self Refresh/Partial Array Self Refresh supported • Auto Pre-charge Mode • DDR Back Up supported • Cache memory for DDR-Memory access efficiency • Memory access protection for secure/safety regions • Decompression of visual near lossless compressed image • ECC supported

1.2.4 Internal Bus Module

Item	Description
AXI-bus	• On-chip main bus — Bus protocol: AXI3 with QoS control — Frequency: 400 MHz — Bus width: 512 bits/256 bits/128 bits • On-chip CPU bus — CoreLink™ CCI-Kipling Cache Coherent Interconnect — Bus protocol: AMBA®4 ACE™ and ACE-Lite™ — Frequency: 800 MHz — Bus width: 128 bits
Direct Memory Access Controller for System (SYS-DMAC)	• 16 channels for PERW domain (SYDM0) • 32 channels for PERE domain (SYDM1, 2) • Address space: 4 GBytes on architecture • Data transfer length: Byte, word (2 Bytes), longword (4 Bytes), 8 Bytes, 16 Bytes, 32 Bytes and 64 Bytes • Maximum number of transfer times: 16,777,215 times • Transfer request: Selectable from on-chip peripheral module request and auto request • Bus mode: Selectable from normal mode and slow mode • Priority: Selectable from fixed channel priority mode and round-robin mode • Interrupt request: Supports interrupt request to CPU at the end of data transfer • Repeat function: Automatically resets the transfer source, destination, and count at the end of DMA transfer (by descriptor function) • Descriptor function (each channel) supported • MMU (each channel) supported • Channel bandwidth arbiter (each channel)
Boot	• System startup with selectable boot mode at power-on reset • Either external ROM boot (area 0) or on-chip ROM boot can be selected through MD pin on development chip. • In on-chip ROM boot, RPC-IF or QSPI serial ROM boot is supported. • Program downloaded to internal memory (System RAM) • Autorun function for the downloaded program • About detail information of BOOT, refer to Section 19 (Boot) and Appendix B (Active sequence).

Item	Description	
Direct Memory Access Controller for Audio (Audio-DMAC)	• 32 channels • asdm0: 16 channels • asdm1: 16 channels • Address space: 4 GBytes on architecture • Data transfer length: Byte, word (2 Bytes), longword (4 Bytes), 8 Bytes, 16 Bytes, 32 Bytes and 64 Bytes • Maximum number of transfer times: 16,777,215 times • Transfer request: Selectable from on-chip peripheral module request and auto request • Bus mode: Selectable from normal mode and slow mode • Priority: Selectable from fixed channel priority mode and round-robin mode • Interrupt request: Supports interrupt request to CPU at the end of data transfer • Repeat function: Automatically resets the transfer source, destination, and count at the end of DMA transfer (by descriptor function) • Descriptor function (each channel) supported • MMU (each channel) supported • Channel bandwidth arbiter (each channel)	
Audio-DMAC-Peripheral-Peripheral	• Audio-DMAC (for transfer from Peripheral to Peripheral) • 29 channels + 29 (extended) channels for audio domain • Data transfer length: longword (4 Bytes) • Transfer count: Transfer count is not specified (DMA transfer is made from the transfer-start to transfer-stop settings.) • Transfer request: Selectable from on-chip audio peripheral module request • Priority: round-robin mode • Interrupt request: not supports interrupt request to CPU at the end of data transfer	
IPMMU	• An IPMMU is a memory management unit (MMU) which provides address translation and access protection functionalities to processing units and interconnect networks.	
Interrupt Controller (INTC)	INTC-AP (for AP-System core Cortex-A57/Cortex-A53)	— 7 interrupt pins which can detect external interrupts — Max. 480 shared peripheral interrupts supported — Fall/rise/high level/low level detection is selectable — On-chip peripheral interrupts: Priority can be specified for each module — 16 software interrupts that have been generated and 6 private peripheral interrupts supported — 32-level priority selectable — Trust Zone supported

1.2.5 Internal Memory

Item	Description
System RAM	RAM of 384 KBytes

1.2.6 Graphics Units

Item	Description
3D Graphics Engine (3DGE)	• Imagination Technologies PowerVR Series 6XT GX6250 • Max. Freq. 600 MHz • Drastically performance improvements for sophisticated graphics and GPU computer • Reducing power consumption even further through advanced power saving mechanisms • Lowest memory bandwidth in the industry with compression technologies • Ultra HD deep color GPU Support APIs: OpenGL ES 3.1, (OpenCL 1.2 EP) • 2.8Gpix/s 350Mpoly/s 112GFLOPS

Item	Description	
Display Unit (DU)	Display channel	3 independently controllable channels
	Interface	• HDMI 1channel (option) • LVDS 1 channel • Digital RGB 1channel (8-bit precision for each RGB color)
	LVDS interface (per channel)	• Output: compliant with TIA/EIA-644; five pairs of differential output (four pairs of data and one pair of clock) • Operating frequency: Dotclk 148.5 MHz
	HDMI (option)	• Support HDMI 1.4 class transfer rate, up to 3D format 1080p60/4Kp30 • Dotclk 297 MHz
	Screen size and number of composite planes per channel	• Maximum screen size: 3840 × 2160 • Number of planes specifiable: 5 (VSP2 processing) • Number of planes specifiable: 1 (DU)
	CRT scanning method	Non-interlaced
	Synchronization method	Master
	Internal color palette (VSP2)	• Includes four color palette planes which can display 256 of 260 thousands colors at the same time.
	Output display numbers	• Three output channels (resolutions for different displays) • Output on rising and falling edges of the synchronizing signal (resolution for the same display) • 8-bit precision for each RGB color
	Blending ratio settings (VSP2)	Number of color palette planes with blending ratio: 4
	Dot clock	Switchable between external input and internal clock
Video Input Module (VIN)	MIPI-CSI2 interface	• 2 channels (4lane × 1channel, 2lane × 1channel) • Interleaving by 4 VC (virtual channel) supported • Filtering by DT (data type) supported • YUV422 8/10bit, RGB888, Embedded 8bit, User Defined 8bit are supported • 1.5Gbps/Lane

Item	Description	
Video Input Module (VIN)	digital interface	• 2 channels (RGB/YCbCr) • Dotclk 100 MHz • ITU-R BT.601 interface: 8-, 10- (same size only (not scaling)), 12- (same size only (not scaling)) 16-, 20- (same size only (not scaling)) or 24-bit (same size only (not scaling)), YCbCr422, 18-bit RGB666, 24-bit RGB888 • ITU-R BT.656 interface: 8-, 10- (same size only (not scaling)), or 12-bit (same size only (not scaling)) YCbCr422 • ITU-R BT.1358 interface: 16-, 20- (same size only (not scaling)), or 24-bit (same size only (not scaling)) YCbCr422 • ITU-R BT.709 interface: 8-, 10- (same size only (not scaling)), 12- (same size only (not scaling)) 16-, 20- (same size only (not scaling)) or 24-bit (same size only (not scaling)) YCbCr422, 18-bit RGB666, 24-bit RGB888 About Digital RGB channel usage combination, Refer as follows cases. CASE1 VIN-A8bit + VIN-B8/12/16 CASE2 VIN-A12bit + VIN-B8/12/16 CASE3 VIN-A16bit + VIN-B8/12
	Capturing function	Up to 8 input images can be captured (using VC, DT filtering)
	Clipping function	Up to 4096 × 4096
	Horizontal scaling	Up to two times, but only scaling down is possible for HD1080i or HD1080p data. (one input only)
	Vertical scaling	Up to three times, but only scaling down is possible for HD1080i or HD1080p data. (one input only)
	Output format	RGB-565, ARGB-1555, ARGB8888, YCbCr422, RGB888, YCbCr420 YC separation, and extraction of the Y component

1.2.7 Video Processing

Item	Description
Video Signal Processor (VSPI)	VSPI has the following features. 1 set of VSPI is integrated. 500 Mpix/s process rate per 1 VSPI Supports 4K (3840 pixels × 2160 lines) processing (1) Supports Various Data Formats and Conversion — Supports YCbCr444/422/420, RGB, αRGB, αplane — Color space conversion and changes to the number of colors by dithering — Color keying — Supports combination between pixel alpha and global alpha — Supports generating pre multiplied alpha (2) Video Processing — Up and down scaling with arbitrary scaling ratio — Super resolution processing — Image rotation/reversal function: Reverses an image vertically/horizontally or rotates it by 90°/270° (3) Picture Quality/Color Correction with 1D/3D Look Up Table (LUT) — Hue, brightness, and saturation adjustment — 1D and 2D histogram Following functions will be supported by Renesas software portfolio. — Dynamic γ correction and gain correction — Correction of color (to adjust skin tones or colors in memory) (4) Visual near lossless image compression supported — 50% of bandwidth is diminished
Video Signal Processor (VSPB)	VSPB has the following features. 1 set of VSPB is integrated. 500 Mpix/s process rate (output rate) per 1 VSPB. Supports 4K (3840 pixels × 2160 lines) processing (1) Supports Various Data Formats and Conversion — Supports YCbCr444/422/420, RGB, αRGB, αplane — Color space conversion and changes to the number of colors by dithering — Color keying — Supports combination between pixel alpha and global alpha — Supports generating pre multiplied alpha (2) Video Processing — Blending of 5 picture layers and raster operations (ROPs) — Vertical flipping (3) Picture Quality/Color Correction with 1D/3D Look Up Table (LUT) — 1D and 2D histogram Following functions will be supported by Renesas software portfolio. — Dynamic γ correction and gain correction — Correction of color (to adjust skin tones or colors in memory) (4) Visual near lossless image compression supported — 50% of bandwidth is diminished

Item	Description
Video Signal Processor (VSPD)	VSPD has the following features. 3 sets of VSPD are integrated. Supports 4K (3840 pixels × 2160 lines) resolution. (1) Supports Various Data Formats and Conversion — Supports YCbCr444/422/420, RGB, αRGB, αplane — Color space conversion and changes to the number of colors by dithering — Color keying — Supports combination between pixel alpha and global alpha — Supports generating pre multiplied alpha (2) Video processing — Blending of 5 picture layers and raster operations (ROPs) — Vertical flipping in case of output to memory (3) Direct connection to display module — Supports 4096 pixels in horizontal direction — Writing back image data which is transferred to Display Unit (DU) to memory

Item	Description
Video Codec Processor (VCP4)	The VCP4 is a multi-codec module which provides encoding and decoding capabilities on the basis of multiple video coding schemes, e.g., H.265/HEVC, H.264/AVC. This IP (Intellectual Property) is a multi codec that processes the frame or each field by controlling software for VCP4 executed on host CPU. • The VCP4 has the following features: Support for multiple codecs H.265/HEVC MP (Main Profile) decoding H.264/MPEG-4 AVC HP (High Profile) and MVC SHP (Stereo High Profile) encoding and decoding • Support for up to 4K resolutions (H.265 and H.264) Multiple channel processing: When iVDP1C is used: (H.264/H.265 1920 × 1080p × 120 fps) When iVDP1C is not used: (H.265 1920 × 1080p × 120 fps) + (H.264 1920 × 1080p × 120 fps) Note: “1920 × 1080p × 120 fps” can be replaced as “3840 × 2160p × 30 fps”. “1920 × 1080p × 60 fps” can be replaced as “1280 × 720p × 120 fps”. “1920 × 1080p × 30 fps” can be replaced as “1280 × 720p × 60 fps”. Maximum performance will change with securable bus bandwidth. • Data handling on a picture-by-picture basis Encodes/decodes data one picture (frame or field) at a time. • High picture quality Supports the H.264 high-efficiency coding tools (CABAC, 8 × 8 frequency conversion, and quantization matrix). High-efficiency motion vector detection by a combination of discrete search and trace search Optimal-mode selection by Rate-Distortion (RD) cost evaluation Picture quality control based on activity analysis results which match visual models • Low power dissipation Dynamically disables the clocks for the entire VCP4. Dynamically disables the clocks for individual submodules. • Includes its own reference data cache • Lossless image compression for reference picture is supported Use the software from Renesas to handle VCP4 functions.
Video Decoding Processor for inter-device video transfer (iVDP1C)	• Low-latency decoder H.264/AVC, JPEG • Color format 4:2:0/4:2:2 • Bit depth 8/10/12bits • Performance: 1280 pixels × 960 lines × 30 frames/second × 4 channels (regardless of when VCP4 is used or not) • Max resolution: 1920 pixels × 1088 lines • Includes its own reference data cache • Lossless image compression for reference picture is supported if bit depth is 8 bits Use the software from Renesas to handle iVDP1C functions.

Item	Description
Fine Display Processor (FDP1)	The FDP1 is the de-interlacing module which converts the interlaced video to progressive video, and has the following features. (1) Supports 1 channel 500 Mpix/s for output performance per 1 FDP1 (2) Supports various data formats — Input: YCbCr444/422/420 — Output: YCbCr444/422/420 and RGB/αRGB (3) 8190 pixels x 8190 lines video processing performance (4) High image quality de-interlacing algorithm — Motion adaptive de-interlacing — Accurate still detection — Diagonal line interpolation (DLI) (5) Visual near lossless image compression supported 50% of bandwidth is diminished

1.2.8 Sound Interface

Item	Description	
Sampling Rate Converter Unit (SCU)	Overall specification	• Includes ten SRC modules — Supports the quality suitable for audio sound (High-sound-quality type) (THD+N -132dB): six modules — Supports the quality suitable for voice sound (general-sound-quality type) (THD+N -96dB): four modules • The SRC module is capable of correcting phase change and delay (timing jitter) generated during data transfer over external memories or external devices. • The channel count conversion unit (CTU), mixer (MIX), and digital mute and volume function (DVC) can be used on two fixed output channels.
	Sampling rate conversion (SRC)	• Capable of asynchronous sampling rate conversion • Supports resolutions up to 24 bits • Two kinds of filter type for SRC. — Supports the quality suitable for audio sound (High-sound-quality type) (THD+N -132dB): Realized the filter by passband -1dB@0.4575FS, cutoff -18dB@0.5FS. — Supports the quality suitable for voice sound (general-sound-quality type) (THD+N -96dB): Realized the filter by passband -1dB@0.4561FS, cutoff -72dB@0.5FS. (Characteristics of each filter is written in the equivalent/up-sampling cases.) • Automatically generates antialiasing filter coefficients • For monaural to eight-channel sound sources
	Channel count conversion unit (CTU)	• Downmixing and splitter functions — Conversion of eight input channels into four output channels — Conversion of six input channels into two output channels — Conversion of two input channels into four sets of two output channels — Conversion of one input channel into eight sets of one output channel — No conversion
	Mixer (MIX)	• Mixing (adds) two to four sources into one • Ratio for adding sources is selectable • Ratio is dynamically changeable • Mixing with volume ramp is available (ramp period is selectable)
	Digital volume and mute function (DVC)	• Volume control function including digital volume, volume ramp, and zero-crossing mute • The digital volume function is specified by a 24-bit fixed-point value within the range from 0 to 8 times (mute, or -120 to 18 dB) • The volume ramp function can be used for soft mute, fade-in, fade-out, or desired volume adjustment • The volume ramp period can be changed within the sampling range from the 0th to 23rd power of 2 • The zero-crossing mute function silences the sound at the zero-crossing point of the audio data

Item	Description	
Serial Sound Interface Unit (SSIU)	Overall specification	• Includes ten SSI modules functioning as interfaces with external devices. — Supports short and long formats for monaural — Supports TDM format (six modules of ten modules can be used for this function) • Max. 16 independent monaural sound sources in a TDM format can be in TDM format.
	Serial sound interface (SSI)	• 10 channels • Max SCK frequency 15.1 MHz (for slave input) or 12.5 MHz (for master output) • Operating mode: non-compressed mode (Not support compressed mode) • Supports versatile serial audio formats (I2S/left justified/right justified) • Supports master/slave functions • Programmable word clock, bit clock generation functions • Multichannel format functions (up to four channels) • Supports 8-/16-/18-/20-/22-/24-bit data formats • Supports TDM mode • Supports WS continue mode • The DMA controller or interrupts control the transfer of data to and from the SSI module. • Supports short and long frames for monaural data (valid data lengths are 8 and 16 bits) • Up to nine independent clock signals can be input.
Audio Clock Generator (ADG)	Selection or division of audio clock signals	

1.2.9 Storage

Item	Description
USB2.0 Host (EHCI/OHCI)	• 2 channels (Host only1 channel/Host-Function 1channel) • USB Host (EHCI/OHCI) 2LINK • (USB3.0 module also can be used as USB2.0) • Compliance with USB2.0 • USB Function 1LINK • Supports On-The-Go (OTG) function Rev2.0 complying with 2 protocols: + Session Request Protocol (SRP). + Host Negotiation Protocol (HNP). • Compliance with USB2.0 (High-Speed) • Interrupt request • Internal dedicated DMA • Compliance with Battery Charging function Rev1.2: + Charging Port (Host): CDP, SDP are supported (Not support DCP). + Portable Device (Function) is supported.
USB3.0 Host Controller	• USB 3.0 DRD 1 channel • This module can be use as USB2.0 as follows • Supports SS/HS/FS/LS. xHCI

Core	Super Speed	High Speed	Full Speed	Low Speed
Host	√	√	√	√
Peripheral	√	√	√	—

SD Card Host Interface (SDHI)	• 4 channels • Supports SDR104 class transfer rate Does not support CPRM • Supports SD memory/SDIO interface • Error check function: CRC7 (command/response), CRC16 (data) • Max Frequency 200 MHz • Card detection function • Supports write protection • SD-binding function — Compliant with Content Protection for Recordable Media Specification in revision 0.92 of the SD-Binding Part of the SD Memory Card Book • SD-SD content protection — Compliant with Content Protection for Recordable Media Specification in revision 0.92 of the SD-SD part of the SD Memory Card Book
Multimedia Card Interface (MMC)	• 2 channels • eMMC 5.0 base, Support HS400 class transfer rate • eMMC controllable • Data bus: 1/4/8-bit MMC mode (not support SPI mode) • Support block transfer (not support stream transfer) • Block size in multiple block transfer: 512 Bytes
rawNAND Controller	• The NAND Flash Memory Interface controller implements the function of a high level interface to one NAND flash device. It supports the functionality of the high speed NAND Flash devices described in the ONFI 1.x specifications.

1.2.10 Network

Item	Description
Controller Area Network Interface (CAN interface)	• 2 interfaces • Supports CAN specification 2.0B • Maximum bit rate: 1 Mbps • Message box — Normal mode: 32 receive-only mailboxes and 32 mailboxes for transmission/reception — FIFO mode: 32 receive-only mailboxes and 24 mailboxes for transmission/reception, 4-stage FIFO for transmission, and 4-stage FIFO for reception • Reception — Data frame and remote frame can be received. — Selectable receiving ID format — Selectable overwrite mode (message overwritten) or overrun mode (message discarded) • Acceptance filter — Mask can be enabled or disabled for each mailbox. • Transmission — Data frame and remote frame can be transmitted. — Selectable transmitting ID format (only standard ID, only extended ID, or both IDs) — Selectable ID priority mode or mailbox number priority mode • Sleep mode for reducing power consumption
CAN-FD	• 2 interfaces • 8 Mbps (CAN clock 40 MHz)
PCIE Controller	• PCI Express Base Specification Revision 2.0 • PHY integrated • 1 Lane × 2 channels (one of PHY is shared with Serial ATA)
EthernetAVB-IF	• Supports IEEE802.1BA, IEEE802.1AS, IEEE802.1Qav and IEEE1722 functions • Supports transfer at 1000 Mbps and 100 Mbps • Magic packet detection • Supports Reception Filtering to separate streaming frames from different sources • Supports interface conforming to IEEE802.3 PHY RGMII (Reduced Gigabit Media Independent Interface) • RGMII v1.3

1.2.11 Timer

Item	Description
RCLK Watchdog Timer	• 1 channel • Internal 16-bit watchdog timer operated by RCLK • Programmable overflow time period: more than 1 hour count capable
16-Bit Timer Pulse Unit (TPU)	• 4-channel 16-bit timers • Each channel outputs PWM

Item	Description
System Watchdog Timer	• 1 channel • Internal 16-bit watchdog timer • Programmable overflow time period: more than 1 hour count capable initial counter value 171[s]
Compare Match Timer Type0 (CMT0)	• 2 channels • 32-bit timer (16 bits/32 bits can be selected) • Source clock: RCLK clock • Compare match function provided • Interrupt requests
Compare Match Timer Type1 (CMT1)	• 8 channels • 48-bit timer (16 bits/32 bits/48 bits can be selected) • Source clock: RCLK/system clock • Compare match function provided • Interrupt requests
Compare match timer 2 (CMT2)	(same as CMT1)
Compare match timer 3 (CMT3)	(same as CMT1)
System Timer	• 32-bit timer, 1channel (16 bits/32 bits can be selected) • Compare match function provided • Interrupt requests
System up-time clock	• 1 channel • Internal 32-bit timer • Programmable overflow time period: maximum 24 hours
Timer Unit (TMU)	• 15 channels • 32-bit timer • Auto-reload type 32-bit down counter • Internal prescaler • Interrupt request • 2 channels for input capture

1.2.12 Peripheral Module

Item	Description
Trusted Secure IP (TSIP)	• Access management unit • Crypto engines • Random number generator • AES, RSA, SHA
IIC Bus Interface for DVFS (IIC for DVFS)	• 1 DVFS channel for dedicated buffer • Supports single master transmission/reception • Interrupt request • Automatic transfer by wakeup / DVFS control
I2C Bus Interface (I2C)	• 7 channels • 4 channels for buffers with a slew rate (channel 0, 3, 4, 5 for dedicated buffers) • 3 channels for LVTTL buffers (channels 1, 2, 6 for ordinary buffers) • NXP I2C bus interface method supported • Master/slave functions • Multi-master functions • Transfer rate up to 400 kbps supported • Programmable clock generation from the system clock • Master and Slave function DMA supported

Item	Description	
Serial communication interface with FIFO (SCIF)	Overall specification	• 6 channels • Asynchronous, clock-synchronized modes • Asynchronous serial communication mode The SCIF performs serial data communication based on a character-by-character asynchronous system. This feature enables serial data communication with standard asynchronous communication chips that support Universal Asynchronous Receiver/Transmitter (UART) or Asynchronous Communication Interface Adapter (ACIA). There is a choice of eight serial data transfer formats. — Data length: 7 bits or 8 bits — Stop bits: 1 bit or 2 bits — Parity: Even/odd/none — Receive error detection: Parity, framing, and overrun errors — Break detection: A break is detected when a framing error lasts for more than 1 frame length at Space 0 (low level). When a framing error occurs, a break can also be detected by reading the RX pin level directly from the serial port register (SCSPTR). • Clock synchronous serial communication mode The SCIF performs serial data communication synchronized with a clock. This feature enables serial data communication with other LSIs that support synchronous communication. There is a single serial data communication format for clock synchronous serial communication. — Data length: 8 bits — Receive error detection: Overrun errors • Full-duplex communication capability The SCIF has an independent transmitter and receiver that enable simultaneous transmission and reception. The transmitter and receiver both have a 16-stage FIFO buffer structure, enabling continuous serial data transmission and reception. • On-chip baud rate generator, enabling any bit rate to be selected The SCIF enables choice of a clock source for transmission/reception: a clock from the on-chip baud rate generator based on the internal clock or an external clock. • Eight interrupt sources The SCIF has eight types of interrupt sources. receive-data-ready, receive-FIFO-data-full, break, transmit-FIFO-data-empty, transmit-end, receive-error, overrun-error and time-out and enables any of them to be requested independently.

Serial Communication Interface with FIFO (SCIF)	Overall specification	• DMA data transfer When the transmit FIFO register is empty or the receive FIFO register has received data, issuing a DMA transfer request activates the DMA controller (DMAC) to execute a data transfer. • In asynchronous mode using channels 0, 1, 3, and 4, modem control functions (RTS and CTS) are stored. • RTS and CTS are not implemented for SCIF2 and SCIF5. • The amount of data in the transmit/receive FIFO registers and the number of receive errors in receive data in the receive FIFO register are available. • In asynchronous mode, a receive data ready (DR) or a timeout error (TO) can be detected during reception.
Clock-Synchronized Serial Interface with FIFO (MSIOF)	• 4 channels • Internal 32-bit × 64-stage transmit FIFOs/internal 32-bit × 256-stage receive FIFOs • Supports master and slave modes • Internal prescaler • Supports serial formats: IIS, SPI (master and slave modes) • Interrupt request, DMAC request	
High Speed Serial Communication Interface with FIFO (HSCIF)	• 5 channels • Asynchronous serial communication mode • Capable of full-duplex communication • On-chip baud rate generator, enabling any bit rate to be selected • Eight interrupt sources • DMA data transfer • Modem control functions (HRTS# and HCTS#) are stored. • The amount of data in the transmit/receive FIFO registers and the number of receive errors in receive data in the receive FIFO register are available. • A receive data ready (DR) or a timeout error (TO) can be detected during reception.	
PWM	• 7 channels • High-level width (10 bits) of PWM output can be set. • Output cycle periods (10 bits) of PWM can be set. • Periods in the range from two to 2^{24} × 1023 cycles of the Pϕ clock can be set. • Continuous pulse or single pulse output selectable	

1.2.13 Others

Item	Description
Boundary Scan (option)	• Boundary scan based on IEEE 1149.1 via JTAG interface is supported. Note that some module pins are not available on this boundary scan.

RZ/G2M
Overview for User’s Manual: Hardware

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